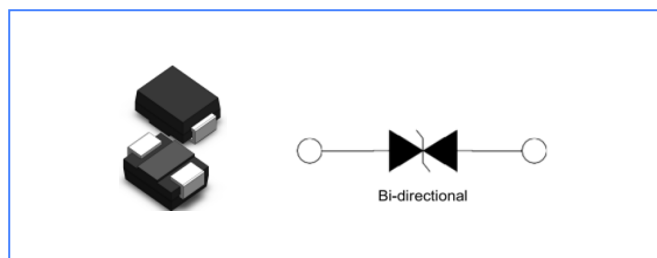


## SMB30J75CA

### Features

- Case: DO-214AA(SMB)
- Excellent clamping capability
- 3000 W peak pulse power capability with a 10/1000  $\mu$ s waveform
- Typical failure mode is a short circuit condition for current events exceeding component rating
- Fast response time: typically less than 1.0ps from 0 Volts to VB min.
- IEC61000-4-2 (ESD)  $\pm$ 15kV (air),  $\pm$ 8kV (contact).

### Functional Diagram



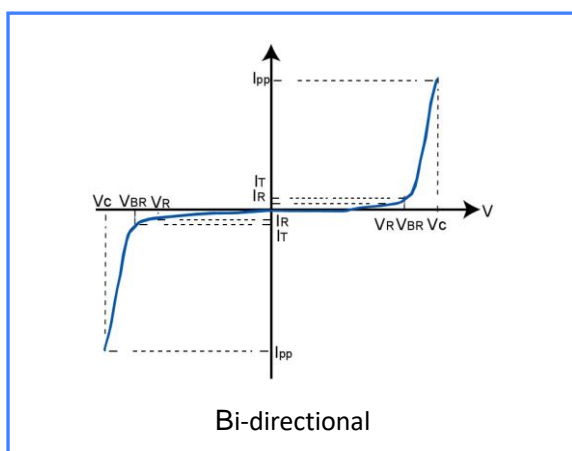
### Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation at $T_A=25^\circ\text{C}$ by 10/1000 $\mu$ s Waveform	P <sub>PK</sub>	3000	W
Operating Temperature Range	T <sub>J</sub>	-55 to +150	$^\circ\text{C}$
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	$^\circ\text{C}$

### Electrical characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

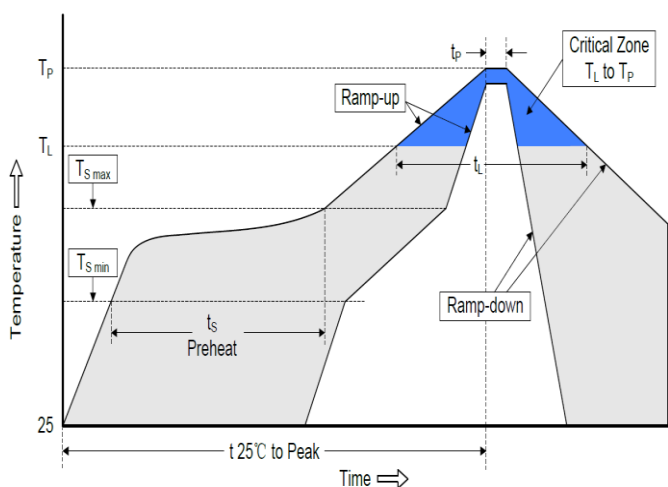
Part Number (Bi)	MARKING	Reverse Stand off Voltage V <sub>R</sub> (Volts)	Breakdown Voltage V <sub>BR</sub> (Volts)@I <sub>T</sub>		Test Current I <sub>T</sub> (mA)	Maximum Reverse Leakage I <sub>R</sub> @ V <sub>R</sub> ( $\mu$ A)	Maximum Peak Pulse Current I <sub>pp</sub> (A)	Maximum Clamping Voltage V <sub>C</sub> @ I <sub>pp</sub> (V)
			Min .V	Max .V				
SMB30J75CA	3DR	75	83.30	92.10	1	1	24.8	121.0

### I-V Curve characteristics



Symbol	Parameter
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
V <sub>RWM</sub>	Working Peak Reverse Voltage
I <sub>R</sub>	Maximum Reverse Leakage Current @V <sub>RWM</sub>
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub> (Test Current)

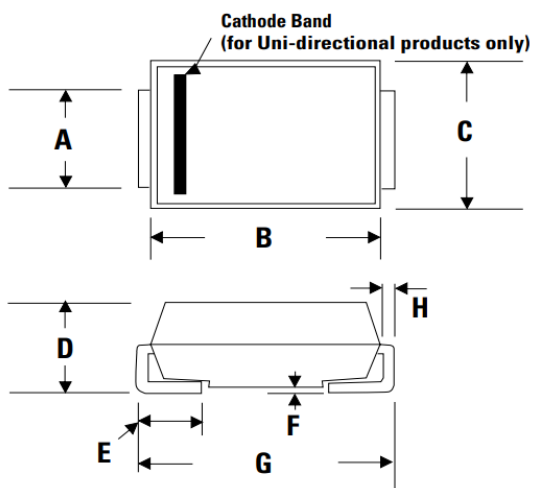
## Soldering parameters



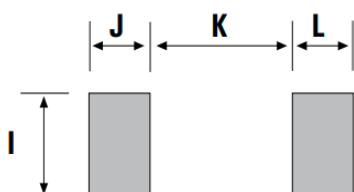
Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat	
-Temperature Min ( $T_{S\ min}$ )	150°C
-Temperature Max ( $T_{S\ max}$ )	200°C
-Time (min to max)( $t_s$ )	60-180 seconds
$T_{S\ max}$ to $T_L$	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_p$ )	20-40 seconds
Ramp-down Rate	6°C /second max.
Time 25°C to Peak Temperature	8 minutes max.

## Package outline dimensions in millimeters

DO-214AA (SMB J-Bend)

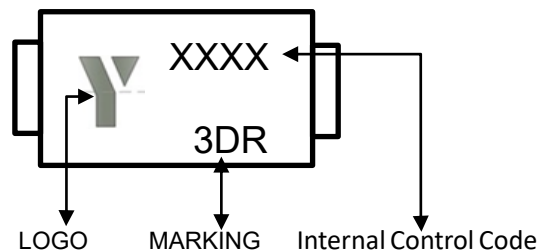
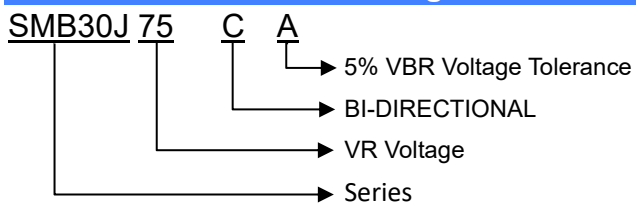


Mounting Pad Layout



Dimensions	Millimeter	
	Min	Max
A	1.930	2.200
B	4.060	4.750
C	3.300	3.940
D	1.990	2.610
E	0.760	1.520
F	-	0.203
G	5.210	5.590
H	0.152	0.305
I	2.260	-
J	2.160	-
K	-	2.740
L	2.160	-

### Part number code & Marking code



### Disclaimer

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.